



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



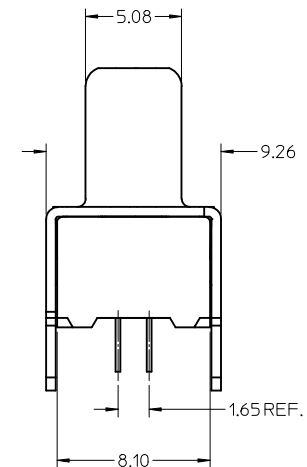
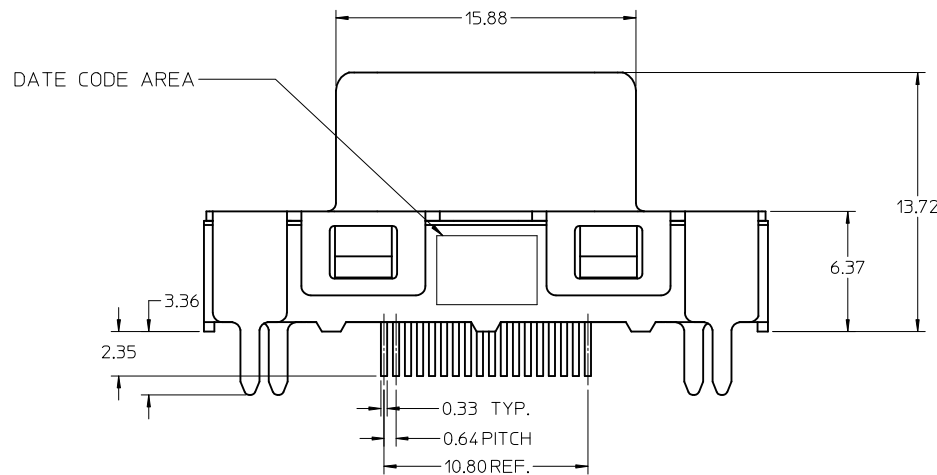
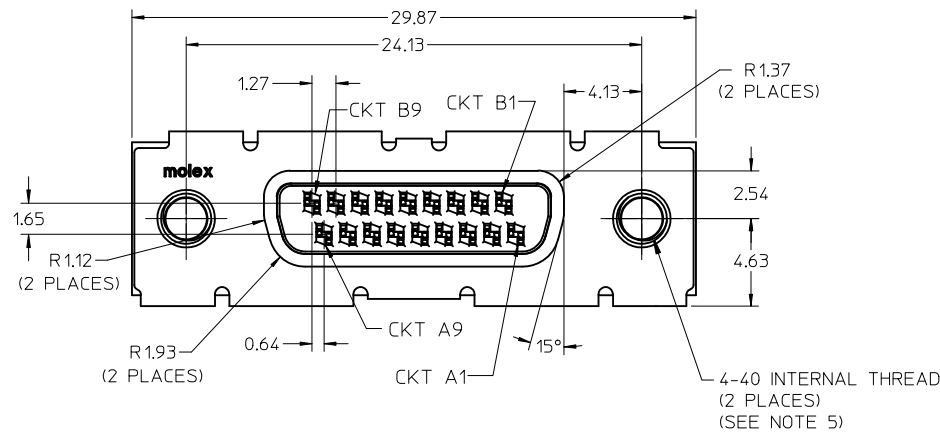
## Contact us

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Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China





NOTES:

1. MATERIALS:

SHIELD: DEEP DRAWN STEEL  
 HOUSING: GLASS FILLED POLYMER, BLACK, UL 94V-0  
 CONTACTS: COPPER ALLOY

2. PLATING:

SHIELD: 2.54 MICROMETERS BRIGHT TIN (Sn) MINIMUM  
 OVER 1.27 MICROMETERS NICKEL (Ni) MINIMUM  
 OVER COPPER (Cu) UNDERPLATE OVERALL.  
 TERMINAL: SELECTIVE GOLD (Au) IN CONTACT AREA,  
 THICKNESS: 0.38 MICROMETERS MINIMUM,  
 SELECTIVE TIN (Sn) IN TAIL AREA,  
 THICKNESS 2.54 MICROMETERS MINIMUM,  
 NICKEL (Ni) UNDERPLATE OVERALL.

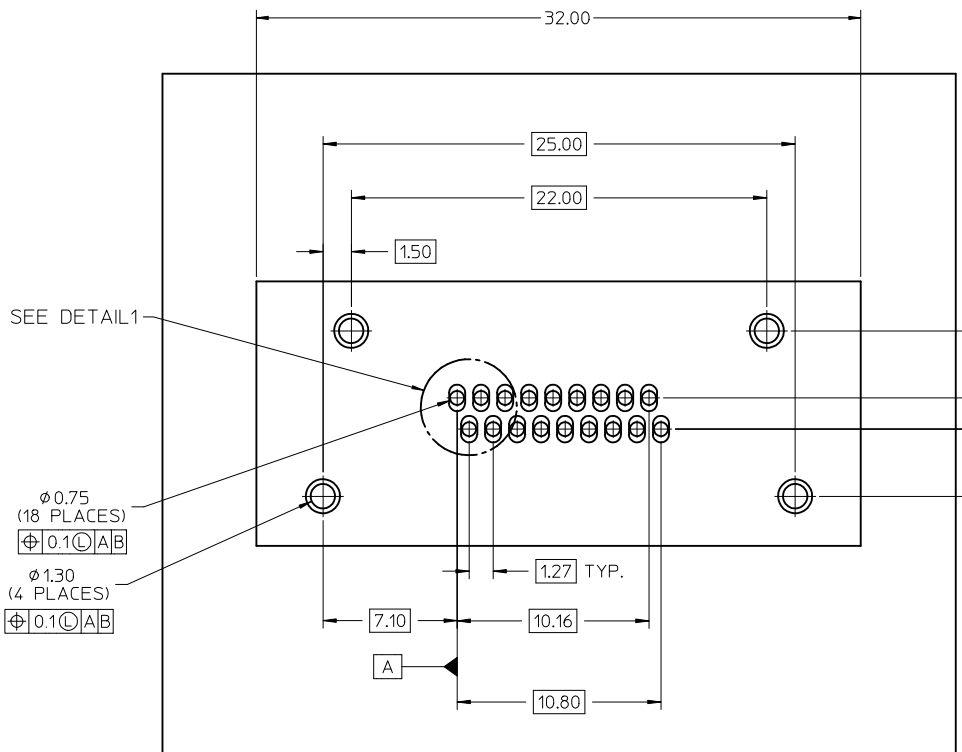
3. PARTS ARE PACKAGED IN TUBES. REFER TO PACKAGING SPECIFICATION PK-74960-995.

4. REFER TO SHEET 2 FOR RECOMMENDED PCB LAYOUT AND PANEL CUT-OUT.

5. PRODUCT CONFORMS TO MOLEX PRODUCT SPECIFICATION PS-74150-001.

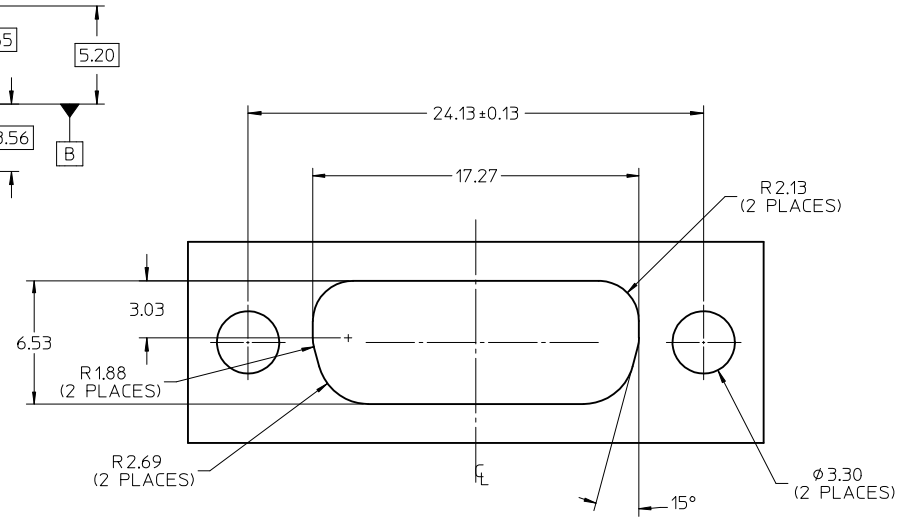
6. OPERATING TEMP RANGE: -40° TO 105°C

ADDED DATE CODE EC NO: UCP2011-0882 DRWN: JJANTELEZIO 2009/12/22 CHKD: APPR: MBANAKIS 2010/10/29 DESCRIPTION	QUALITY SYMBOLS	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE	SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION
	$\nabla=0$ $\nabla=0$	mm	INCH	MM ONLY	5:1	METRIC	
		4 PLACES ± ---	± ---	DRAWN BY	DATE	TITLE	
		3 PLACES ± ---	± ---	JJANTELEZIO	06/05/2008	VERTICAL TDP FOR PCIe 1X	
	2 PLACES ± 0.13	± ---	CHECKED BY	DATE			
	1 PLACE ± 0.25	± ---	APPROVED BY	DATE			
		ANGULAR ± 1/2°	MBANAKIS	2010/10/29			
			MATERIAL NO.	766410001	MOLEX INCORPORATED		
			DOCUMENT NO.	SD-76641-001	SHEET NO.		
			SIZE	C	1 OF 3		
			THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION				

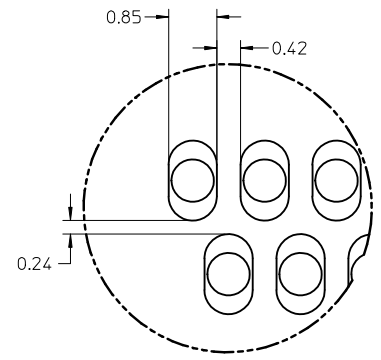


SEE DETAIL1

- Ø 0.75  
(18 PLACES)  
⊕ 0.1 Ⓞ AB
- Ø 1.30  
(4 PLACES)  
⊕ 0.1 Ⓞ AB



2.03 MAX  
PANEL THICKNESS



DETAIL1  
SCALE 15:1

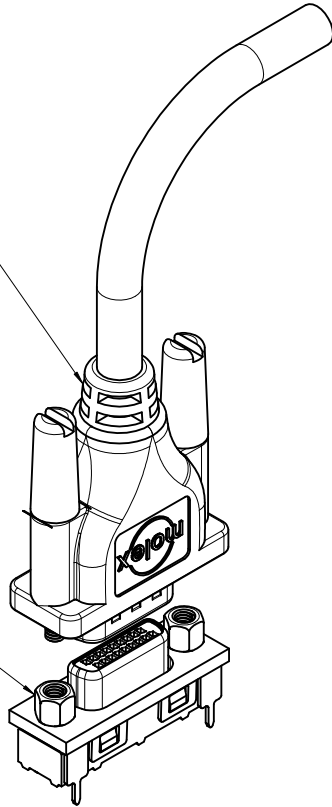
<b>SEE SHEET 1</b> EC NO: UCP2011-0882 DRAWN: JANTELEZIO 2009/12/22 CHKD: MBANAKIS 2010/10/29 APPR: MBANAKIS	QUALITY SYMBOLS ▽=0 ▽=0	GENERAL TOLERANCES (UNLESS SPECIFIED) <table border="1"> <thead> <tr> <th></th> <th>mm</th> <th>INCH</th> </tr> </thead> <tbody> <tr> <td>4 PLACES</td> <td>± 0.25</td> <td>± 0.010</td> </tr> <tr> <td>3 PLACES</td> <td>± 0.25</td> <td>± 0.010</td> </tr> <tr> <td>2 PLACES</td> <td>± 0.13</td> <td>± 0.005</td> </tr> <tr> <td>1 PLACE</td> <td>± 0.25</td> <td>± 0.010</td> </tr> </tbody> </table>		mm	INCH	4 PLACES	± 0.25	± 0.010	3 PLACES	± 0.25	± 0.010	2 PLACES	± 0.13	± 0.005	1 PLACE	± 0.25	± 0.010	DIMENSION STYLE <b>MM ONLY</b> DRAWN BY: JJANTELEZIO DATE: 06/05/2008 CHECKED BY: _____ DATE: _____	SCALE <b>5:1</b> DESIGN UNITS <b>METRIC</b> THIRD ANGLE PROJECTION	TITLE <b>VERTICAL TDP FOR PCIE 1X</b>
		mm	INCH																	
	4 PLACES	± 0.25	± 0.010																	
	3 PLACES	± 0.25	± 0.010																	
2 PLACES	± 0.13	± 0.005																		
1 PLACE	± 0.25	± 0.010																		
APPROVED BY: MBANAKIS DATE: 2010/10/29 MATERIAL NO.	APPROVED BY: _____ DATE: _____ MATERIAL NO.	MOLEX INCORPORATED DOCUMENT NO.	SHEET NO. <b>2 OF 3</b>																	
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	SEE SHEET 1	SD-76641-001	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION																	

STANDARD CONFIGURATION

OPTIONAL CONFIGURATION

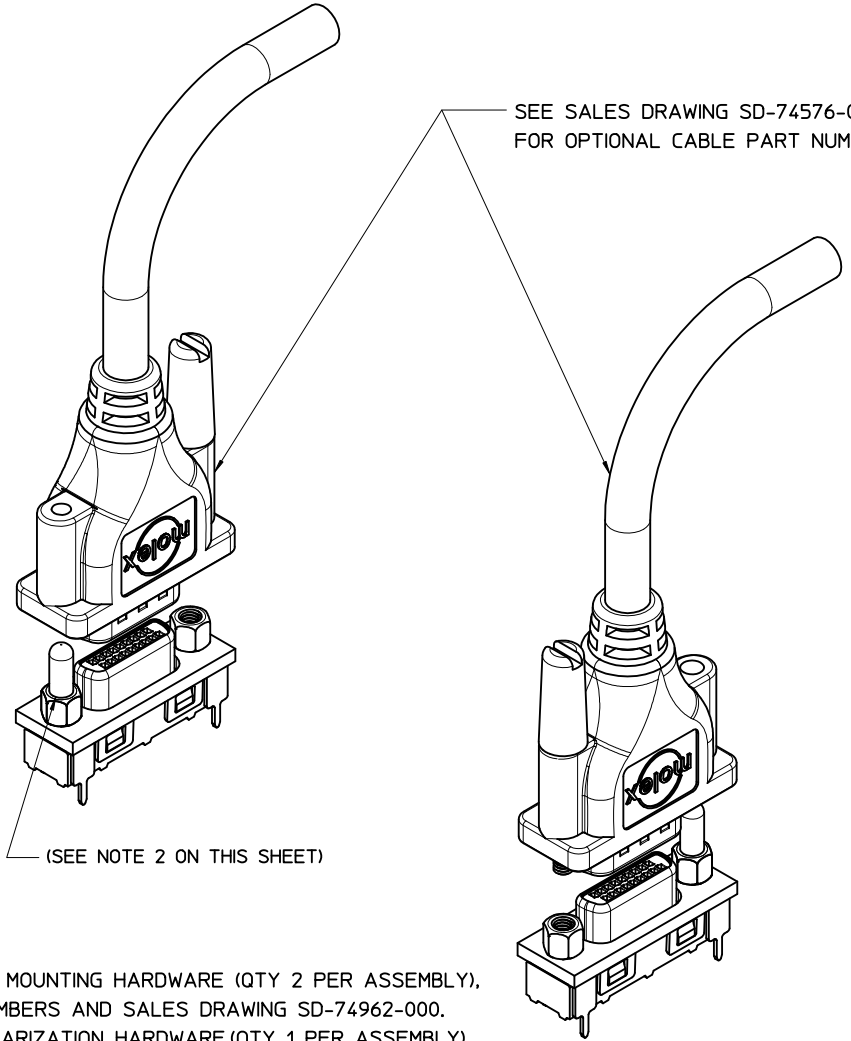
SEE SALES DRAWING SD-74576-000  
FOR STANDARD CABLE PART NUMBER

(SEE NOTE 1 ON THIS SHEET)

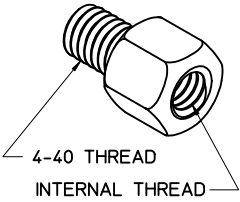
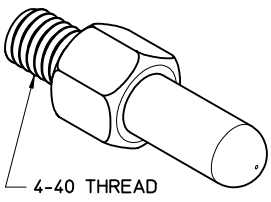


SEE SALES DRAWING SD-74576-0300  
FOR OPTIONAL CABLE PART NUMBER

(SEE NOTE 2 ON THIS SHEET)



1. RECOMMENDED JACK POST MOUNTING HARDWARE (QTY 2 PER ASSEMBLY), SEE CHART FOR ITEM NUMBERS AND SALES DRAWING SD-74962-000.
2. OPTIONAL JACK POST POLARIZATION HARDWARE.(QTY 1 PER ASSEMBLY), SEE CHART FOR ITEM NUMBER AND SALES DRAWING SD-74962-100.

RECOMMENDED JACKPOST INTERNAL THREAD OPTIONS (SEE NOTE 1 ON THIS SHEET)		OPTIONAL JACKPOST POLARIZATION HARDWARE (SEE NOTE 2 ON THIS SHEET)
4-40	M3	
74962-0003	74962-0004	74962-0200
		
4-40 THREAD INTERNAL THREAD	4-40 THREAD	

SEE SHEET 1 EC NO: UCP2011-0882 DRAWN: JANTELEZIO 2009/12/22 CHKD: APPR: MBANAKIS 2010/10/29 REV	QUALITY SYMBOLS	GENERAL TOLERANCES (UNLESS SPECIFIED)	DIMENSION STYLE <b>MM ONLY</b>	SCALE <b>2:1</b>	DESIGN UNITS <b>METRIC</b>	THIRD ANGLE PROJECTION
	▽=0	mm INCH	DRAWN BY JJANTELEZIO	DATE 06/05/2008	TITLE <b>VERTICAL TDP FOR PCIE 1X</b>	
	▽=0	4 PLACES ± --- ± ---	CHECKED BY	DATE	APPROVED BY MBANAKIS	
	▽=0	3 PLACES ± --- ± ---	DATE 2010/10/29		DATE	
		2 PLACES ±0.13 ± ---	APPROVED BY DATE		MOLEX INCORPORATED	
		1 PLACE ±0.25 ± ---	MATERIAL NO.		DOCUMENT NO.	
		ANGULAR ±1/2°	DATE		SHEET NO.	
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE SHEET 1		SD-76641-001		3 OF 3
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